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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

FEB 28 2003  
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In re Application of: Agarwala et al.

Docket No.: BUR920000215US1

TECHNOLOGY CENTER

Serial No.: 09/871,883

Group Art Unit: 2815

Filed: June 1, 2001

Examiner: Warren, Matthew E.

Title: DUAL-DAMASCENE MULTI-LEVEL METALLIZATION

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Okay to  
enter Amdt B.  
mew  
3/11/04

This paper is being filed in response to the Final Office Action mailed on January 13, 2003. Applicants request this Amendment be entered in the above-identified application and reconsideration of the application in view of the Amendments and Remarks that follow.

AMENDMENT

Please amend the above-referenced patent application as follows:

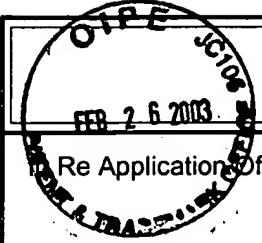
In The Claims

Please amend claims 1, 10, 20 and 25 as indicated in Appendix A. The amendments of claims 1, 10, 20 and 25 are not made in response to the Examiners rejection and do not raise new issues but are made for the purpose of clarification. Currently pending claims 1-4, 6-13, 15-20, 22-25, 27-35, are as follows:

1. (Twice amended) An interconnect structure, comprising:

a lower level wire in a dielectric layer, said lower level wire having a side and a bottom, said lower level wire comprising a lower core conductor and a lower conductive liner, said lower conductive liner on the side and the bottom of said lower level wire, said lower conductive liner

2815



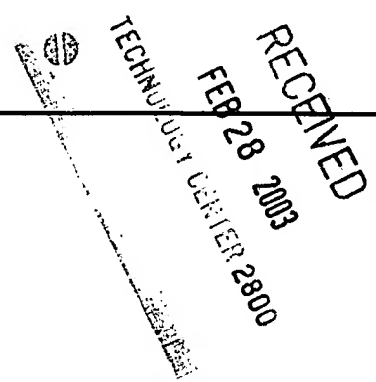
**TRANSMITTAL LETTER**  
**(General - Patent Pending)**

Docket No.  
**BUR920000215US1**

Re Application Of: **Agarwala et al.**

Serial No.	Filing Date	Examiner	Group Art Unit
09/871,883	6/1/2001	Warren, Matthew E.	2815

Title: **DUAL-DAMASCENE MULTI-LEVEL METALLIZATION**



TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is:

**Amendment**  
**IDS with 3 references**

in the above identified application.

- ☒ No additional fee is required.
- ☐ A check in the amount of \_\_\_\_\_ is attached.
- ☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **09-0456(IBM)** as described below. A duplicate copy of this sheet is enclosed.
  - ☐ Charge the amount of \_\_\_\_\_
  - ☒ Credit any overpayment.
  - ☒ Charge any additional fee required.

Jack P. Friedman  
Signature

Dated: **2/21/2003**

**Jack P. Friedman**  
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I certify that this document and fee is being deposited on 2/21/2003 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Signature of Person Mailing Correspondence

**Kim Dwileski**

Typed or Printed Name of Person Mailing Correspondence

CC: